

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CHE-CHENG CHANG	03/03/2016
	CHIH-HAN LIN	03/03/2016
	HORNG-HUEI TSENG	03/07/2016
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300-78	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	15071213	
CORRESPONDENCE DATA		
Fax Number:	(510)580-7280	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Email:	usa@jcipgroup.com.tw	
Correspondent Name:	JIANQ CHYUN INTELLECTUAL PROPERTY OFFICE	
Address Line 1:	7F.-1, NO. 100, ROOSEVELT RD., SEC. 2,	
Address Line 4:	TAIPEI, TAIWAN 100	
ATTORNEY DOCKET NUMBER:	61537-US-PA	
NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	
DATE SIGNED:	03/16/2016	
Total Attachments: 3		
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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

INTERCONNECTION AND MANUFACTURING METHOD THEREOF

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Che-Cheng Chang Date: 2016/3/3
Legal Name of Sole or First Inventor: Che-Cheng Chang
Residence: New Taipei City, Taiwan
Mailing Address: No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chih-Han Lin Date: 2016/3/3
Legal Name of Additional Joint Inventor, if any: Chih-Han Lin
Residence: Hsinchu City, Taiwan
Mailing Address: No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Hong-Huei Tseng Date: March 7, 2016
Legal Name of Additional Joint Inventor, if any: Hong-Huei Tseng
Residence: Hsinchu City, Taiwan
Mailing Address: No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.